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(54) **HEAT DISSIPATION APPARATUS AND SERVER**

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(57) **ABSTRACT**

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A heat dissipation apparatus including an air-cooling structure and a liquid-cooling structure, and a server are provided. The air-cooling structure is configured to simultaneously perform air cooling on a first-type component and a second-type component, and the liquid-cooling structure is configured to perform liquid cooling on the first-type component, where heat generated by the first-type component is higher than heat generated by the second-type component. The liquid-cooling structure specifically includes a liquid-cooling assembly and a heat exchanger. The liquid-cooling assembly can conduct the heat generated by the first-type component into a coolant in a liquid-cooling pipe of the liquid-cooling assembly. The heat exchanger is configured for heat exchange between the coolant and external air, and the heat exchanger herein is disposed at a tail end of the server.

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